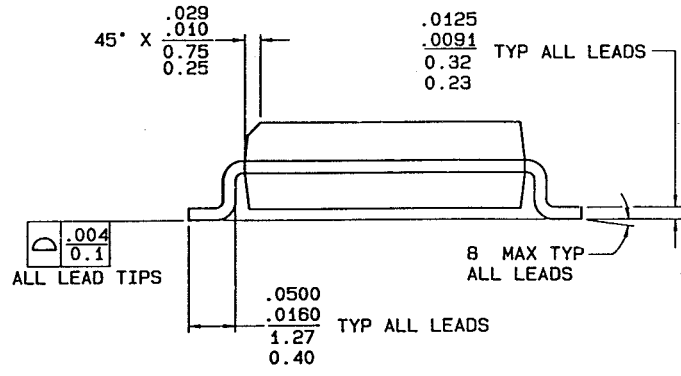
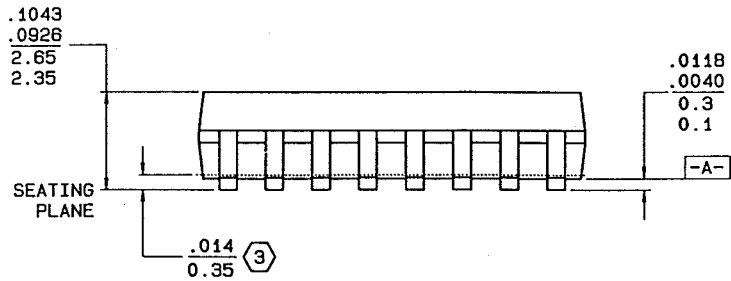
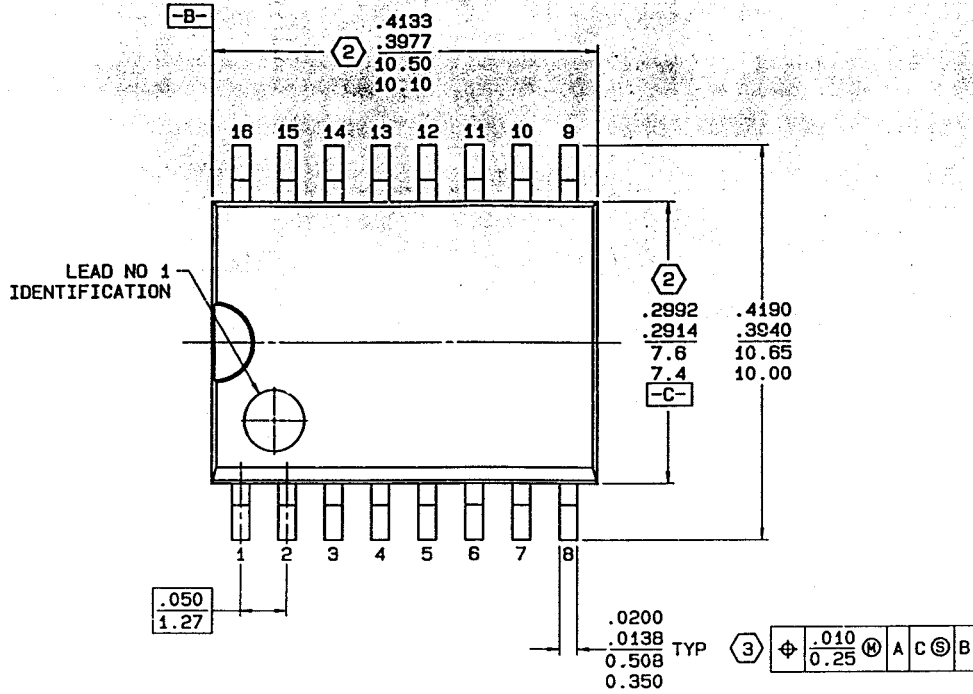


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
	REVISED AND REDRAWN	04103	02/17/87	JIM/CC
E	REVISE OVERALL PKG SIZE, LEAD CONFIG & NOTES TO INCORP FSC PARTS. DELETE PKG UPPER HALF DIM. & DIM FROM PKG EDGE TO LEAD 1 CTR LINE.	05928	10/05/88	GVZ/CC
F	REMOVE LEAD TAPER; DEL. NOTE 4.	07884	04/05/90	SL6/CL



NOTES: UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH:
200 MICROINCHES/5.08 MICRONS MINIMUM
LEAD/TIN (SOLDER) ON COPPER.

(2) THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH.

(3) MAXIMUM LEAD WIDTH ABOVE AREA SPECIFIED
.024/0.609.

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN JIM WINNETT	02/17/87	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DRG. CHK. Marta Ruby	04/16/90	MOLDED PACKAGE, S.O., .300 WIDE, 16 LEAD		
ENGR. C. Chua	4/16/90			
APPROVAL		SCALE N/A	SIZE C	DRAWING NUMBER MKT-M16B
PROJECTION 		DO NOT SCALE DRAWING		REV F
		SHEET 1 OF 1		